

## Claims

What is claimed is:

1. A process of making a laser diode device, including the following steps:
  - (a) applying a bonding layer to a cavity surface of a first body of dielectric material;
  - (b) applying a bonding layer to a cavity surface of a second body of dielectric material;
  - (c) bonding a conductor ring to said bonding layer of said first body;
  - (d) mounting said second body over said first body and said conductor ring, whereby said said first and second bodies together substantially surround said conductor ring; and
  - (e) bonding said conductor ring to said bonding layer of said second body
2. A process as defined in claim 1, in which said bonding layer is molybdenum manganese.
3. A process as defined in claim 1, in which said cavity surface is semi-cylindrical and said conductor ring is a sectored conductor ring.
4. A process as defined in claim 1, in which said bonding is by copper-silver solder.
5. A process as defined in claim 1, in which said dielectric material is beryllium oxide.
6. A process of making a laser diode device, including the following steps:
  - (a) applying a bonding layer to a cavity surface of a first body of dielectric material;
  - (b) applying a bonding layer to a cavity surface of a second body of dielectric material;
  - (c) joining said first and second bodies together to form a closed cavity therebetween; and
  - (d) bonding a conductor ring to said bonding layers of said first and second bodies.
7. A process as defined in claim 6, in which said bonding layer is molybdenum manganese.
8. A process as defined in claim 6, in which said cavity surface is semi-cylindrical and said conductor is a sectored conductor ring.
9. A process as defined in claim 6, in which said bonding is by copper-silver solder.
10. A process as defined in claim 6, in which said dielectric material is beryllium oxide.